Serial No. 09/905,172



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: David S. Mui et al.

Serial No.: 09/905,172

Filed: 07/13/2001

Title: ETCH PATTERN DEFINITION USING A CVD ORGANIC LAYER AS AN

ANTI-REFLECTION COATING AND HARDMASK

Art Unit: 1765

Examiner: Deo, Duy Vu Nguyen

Docket No.: 004227USA02/ETCH/SILICON

VIA FACSIMILE 703-872-9310 Mail Stop Fee Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE

Sir:

Responsive to the Office Action mailed June 10, 2003 in the above matter, Applicants submit the following amendment and remarks.



251 North Avenue West, 2nd Floor Westfield, NJ 07090

13164 Lazy Glen Lane Oak Hill, Virginia 20171

Mayer, Fortkort & Williams, PC **Attorneys At Law**





Toı	Commissioner for Pater	its	From:	David Bonham (703) 433-0510
Faoc:	703-872-9310		Total pages:	11
Phones	 		Date:	9/10/2003
Re:	In connection with prosecution in Serial. No. 09/905,172, please find enclosed (a) an Amendment and Response and (b) a Terminal Disclaimer to Obviate a Double Patenting Rejection over a Prior Patent.		CCi	
	David Bonham			
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